<table>
<thead>
<tr>
<th>Object</th>
<th>Missing</th>
<th>Material Type</th>
<th>Part No.</th>
<th>Comment</th>
</tr>
</thead>
<tbody>
<tr>
<td>D</td>
<td>5</td>
<td>RotoPAK</td>
<td>D10</td>
<td></td>
</tr>
<tr>
<td>E</td>
<td>5</td>
<td>RotoPAK</td>
<td>D20</td>
<td></td>
</tr>
<tr>
<td>D</td>
<td>5</td>
<td>RotoPAK</td>
<td>D30</td>
<td></td>
</tr>
<tr>
<td>D</td>
<td>5</td>
<td>RotoPAK</td>
<td>D40</td>
<td></td>
</tr>
</tbody>
</table>

**ALL ATTACH VIEWS FROM TOP VIEW**

**BOM NO.** 12/01-01527
**DRAWN BY** EI
**SIN DRA Hot In HaraseControl**

**LAYER NAME** = Drill Drawing
**TOP**

**FILH NAME** = Drill Drawing
**GENERATED** 12/01-18
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